

# Description

The HL3053S1 series of devices each consist of a GaAs infrared emitting diode optically coupled to a monolithic silicon non zero voltage crossing photo triac. They are designed for use with a discrete power triac in the interface of logic systems, such as solid-state relays, industrial controls, motors, solenoids and consumer appliances.



#### **Features**

- 6pin Non-zero-cross optoisolators triac driver
- High input-output isolation voltage(Viso = 5,000Vrms)
- High repetitive peak off-state voltage VDRM.
- Min.600V;
- High critical rate of rise of off-state voltage( dv/dt : MIN. 1000V/s )
- Operating Temperature: -40 °C ~110 °C
- RoHS

## **Applications**

- Solenoid/valve controls
- Static power switch
- AC motor drivers
- Temperature Control

# Pin Configuration 1 Anode 2 Cathode 3 No Connection 4 Terminal 5 No Connection (do not connect)

## **Maximum Ratings**

Parameter		Symbol	Values	Unit
	Forward Current	lF	50	mA
Input	Reverse Voltage	VR	6	V
	Power Dissipation	Р	120	mW
	Junction Temperature	TJ	125	$^{\circ}$
Output	Off-State Output Terminal Voltage	V <sub>DRM</sub>	600	V
	Peak Repetitive Surge Current (PW=1ms, 120 pps)	Ітѕм	1	А
	On-State RMS Current	I <sub>T(RMS)</sub>	100	mA ℃
	Junction Temperature	TJ	125	
	Collector Power Dissipation	Pc	150	mW
Operating temperature range		Topr	- 40 ~ 110	°C
Storage temperature range		T <sub>stg</sub>	- 55 ~ 125	°C
Total Power consumption		P(w)	250	mW
Isolation Voltage <sup>(1)</sup>		Viso	5000	Vrms
Soldering Temperature <sup>(2)</sup>		TsoL	260	° C

#### Notes

- (1). AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.
- (2). For 10 seconds



# **Electronic Optical Characteristics (TA = 25°C)**

Parameter		Symbol	Min.	Тур.	Max.	Unit	Conditon
Input	Forward Voltage	$V_{F}$	-	1.2	1.6	V	I <sub>F</sub> =20mA
	Reverse Current	$V_{R}$	-	-	5	μA	V <sub>R</sub> =6V
Output	Peak Blocking Current, Either Direction (1)	I <sub>DRM</sub>	-	-	500	nA	V <sub>DRM</sub> = Rated VDRM
	Peak On-State Voltage, Either Direction	$V_{TM}$	-	-	3	V	I <sub>TM</sub> = 100mA Peak
	Critical rate of Rise of Off-State Voltage (2)	dv/dt	1000	-	-	V/µs	Vin=240Vrms
Couple	Led Trigger Curren Current Required to Latch Output, Either Direction	t, I <sub>FT</sub>	-	-	5	mA	Main Terminal Voltage = 3V
	Holding Current, Either Direction	lн	-	200	-	uA	-

 $<sup>(1) \ \</sup> Test\ voltage\ must\ be\ applied\ within\ dv/dt\ rating.$ 

<sup>(2)</sup> This is static dv/dt. Commutating dv/dt is a function of the load-driving thyristor(s) only.



## **Characteristics Curves**

Fig.1 Forward current vs. Ambient temperature

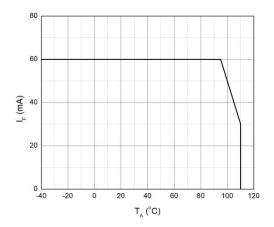


Fig.2 On-state current vs.Ambient temperature

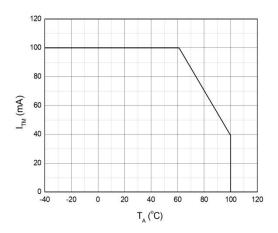


Fig.3 Forward current vs Forward Voltage

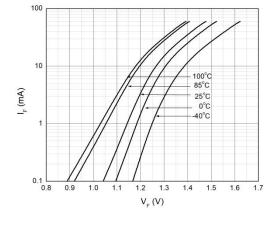


Fig.4 Holding current vs Ambient temperature

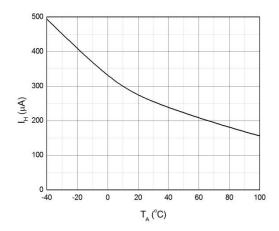
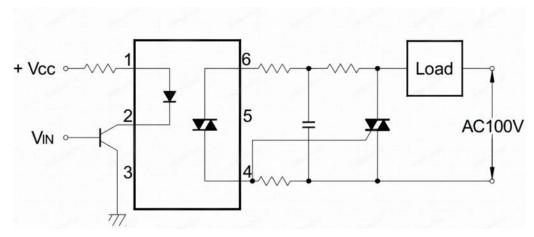
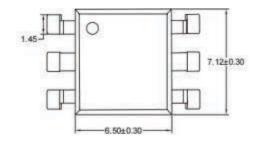


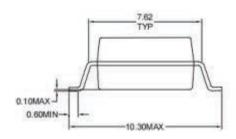
Fig.9 Basic Driver Circuit

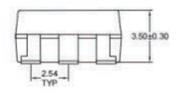


## **Outline Dimension**

# SMD-6 Type:





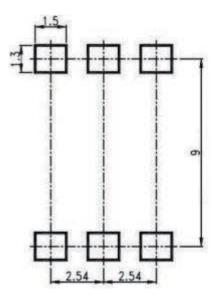


Unit: mm

Tolerance: ±0.1mm



# Recommended solder pad Design



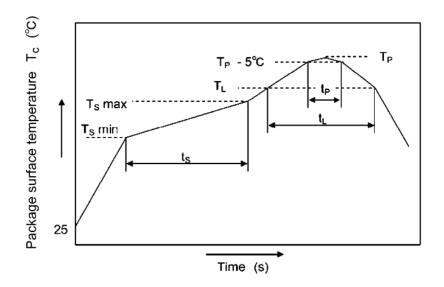
Unit: mm

Tolerance: ±0.1mm

## **Temperature Profile Of Soldering**

# 1. IR Reflow soldering (JEDEC-STD-020D compliant)

Profile item	Conditon			
Preheat				
-Temperature Min (TSmin)	150°C			
-Temperature Max (TSmax)	200°C			
-Time (min to max) (ts)	90±30 sec			
Soldering zone				
-Temperature (TL)	217°C			
-Time (t∟)	60-150 sec			
Peak Temperature (TP)	260°C			
-Time (TP-5℃to TP) (ts)	30 sec			
Ramp-up rate	3°C / sec max			
Ramp-down rate	3~6°C/ sec			



#### Notes:

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

## 2. Wave soldering (JEDEC22A111 compliant)

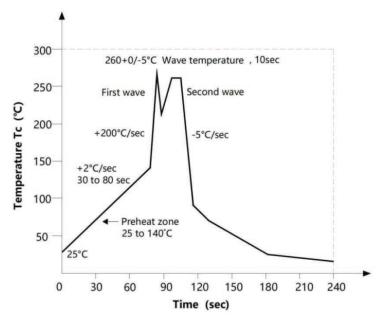
One time soldering is recommended within the condition.

Temperature:260+0/-5°C.

Time:10 sec.

Preheat temperature:25 to 140°C.

Preheat time:30 to 80 sec.



## 3. Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5°C

Time: 3 sec max.



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